

HALOGEN FREE



# N-Channel 40-V (D-S) MOSFET

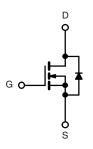
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)	
40	0.0088 at V <sub>GS</sub> = 10 V	50	16 nC	
40	0.0105 at V <sub>GS</sub> = 4.5 V	50	10110	

#### **FEATURES**

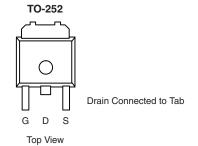
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % UIS Tested
- 100 % R<sub>q</sub> Tested
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

- · LCD Display Backlight Inverters
- DC/DC Converters



N-Channel MOSFET



Ordering Information: SUD50N04-8m8P-4GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	40	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V
-	T <sub>C</sub> = 25 °C		50 <sup>a</sup>	
Continuous Drain Current (T. 150 °C)	T <sub>C</sub> = 70 °C		44	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	14 <sup>b</sup>	
	T <sub>A</sub> = 70 °C		11.2 <sup>b</sup>	
Pulsed Drain Current		I <sub>DM</sub>	100	Α
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	- I <sub>S</sub>	40	]
	T <sub>A</sub> = 25 °C		2.6 <sup>b</sup>	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	30	
Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	45	mJ
	T <sub>C</sub> = 25 °C	P <sub>D</sub>	48.1	w
Maximum Power Dissipation	T <sub>C</sub> = 70 °C		30.8	
	T <sub>A</sub> = 25 °C		3.1 <sup>b</sup>	
	T <sub>A</sub> = 70 °C		2.0 <sup>b</sup>	]
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	$R_{thJA}$	32	40	°C/W
Maximum Junction-to-Case	Steady State	$R_{thJC}$	2.1	2.6	O/ <b>VV</b>

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.

Document Number: 68647 S10-0109-Rev. B, 18-Jan-10

# SUD50N04-8m8P

# Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					L	L	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	40			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 10		44		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 1.0 mA		- 5.9			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.5		3.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zava Cata Valtana Duain Commant		V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V			1	μА	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C			20		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Dunin Course On Otata Basistanasi		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0069	0.0088		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.0084	0.0105	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		75		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			2400		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		260			
Reverse Transfer Capacitance	C <sub>rss</sub>			100			
Total Cata Charres		$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		37	56	nC	
Total Gate Charge				16	24		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		6.5			
Gate-Drain Charge	Q <sub>gd</sub>			4.5			
Gate Resistance	$R_{g}$	f = 1 MHz	2.5	5.5	8.5	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			30	45		
Rise Time t <sub>r</sub>		$V_{DD} = 20 \text{ V}, R_L = 1 \Omega$		15	25		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		45	70	ns	
Fall Time	t <sub>f</sub>			15	25		
Turn-On Delay Time	t <sub>d(on)</sub>			9	15		
Rise Time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_L = 1 \Omega$		5	10		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		40	60		
Fall Time	t <sub>f</sub>			5	10		
<b>Drain-Source Body Diode Characteris</b>	tics						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			40	Α	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				100	^	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 10 A		0.81	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			22	35	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 20 A dl/dt = 100 A/vs T = 05 °C		14	25	nC	
Reverse Recovery Fall Time t <sub>a</sub>		$I_F = 20 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		11			
Reverse Recovery Rise Time	t <sub>b</sub>			11		ns	

#### Notes:

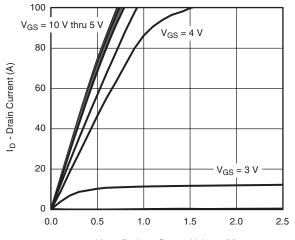
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

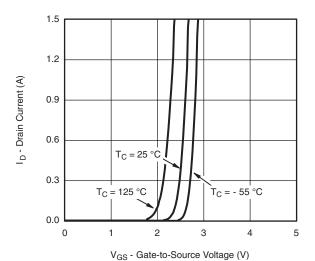


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

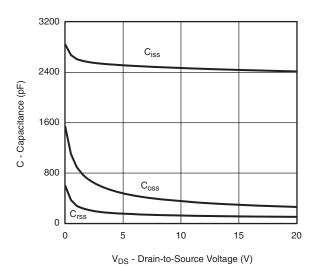


V<sub>DS</sub> - Drain-to-Source Voltage (V)

#### **Output Characteristics**



Transfer Characteristics

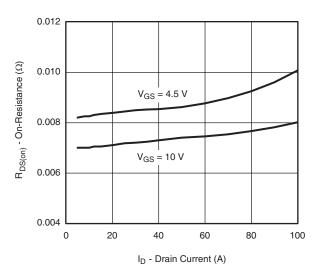


Capacitance

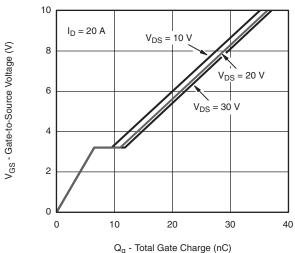
(V) tuguno uiguo 60 T<sub>C</sub> = 25 °C T<sub>C</sub> = -55 °C T<sub>C</sub> = -55 °C

 $V_{\text{GS}}$  - Gate-to-Source Voltage (V)

#### Transfer Characteristics



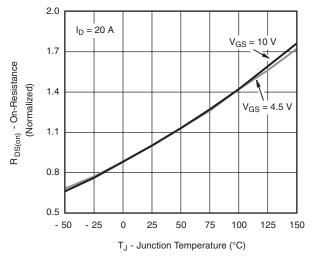
On-Resistance vs. Drain Current



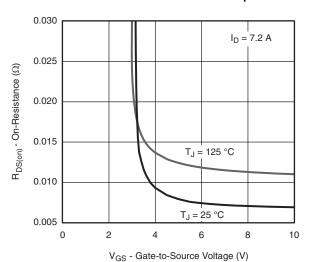
Gate Charge

## Vishay Siliconix

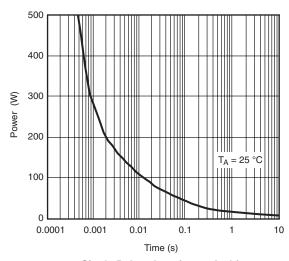
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



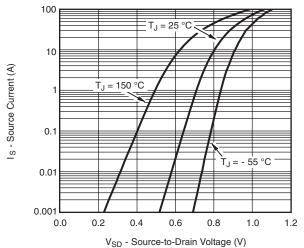
#### On-Resistance vs. Junction Temperature



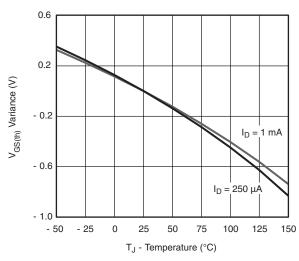
On-Resistance vs. Gate-to-Source Voltage



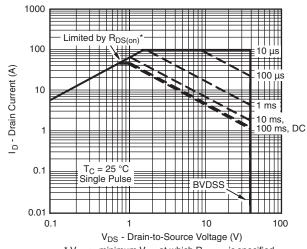
Single Pulse, Junction-to-Ambient



Source-Drain Diode Forward Voltage



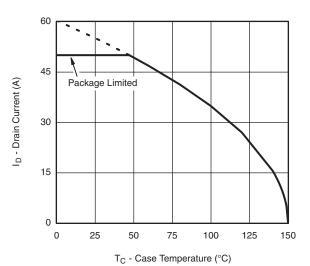
**Threshold Voltage** 



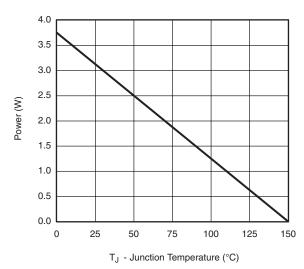
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

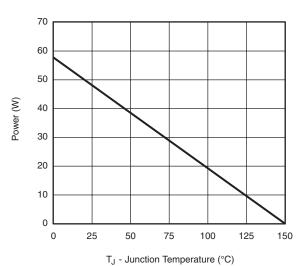


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



#### Current Derating\*, Junction-to-Case





Power Derating, Junction-to-Ambient

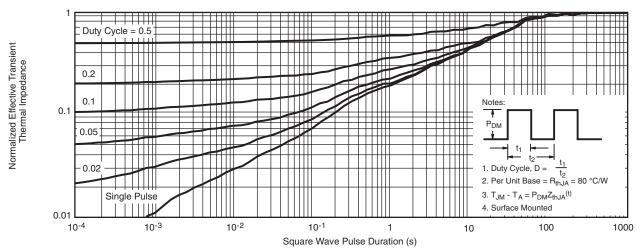
Power Derating, Junction-to-Case

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

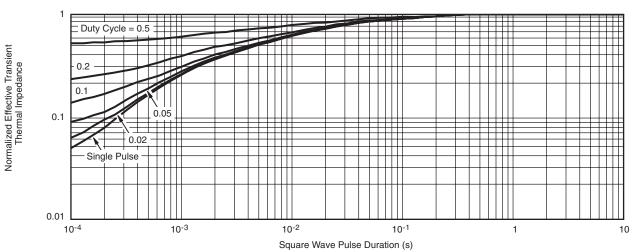
## Vishay Siliconix



### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



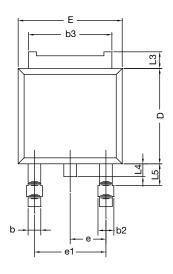
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?68647">www.vishay.com/ppg?68647</a>.

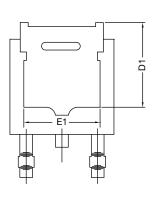


TO-252AA Case Outline

#### **VERSION 1: FACILITY CODE = Y**







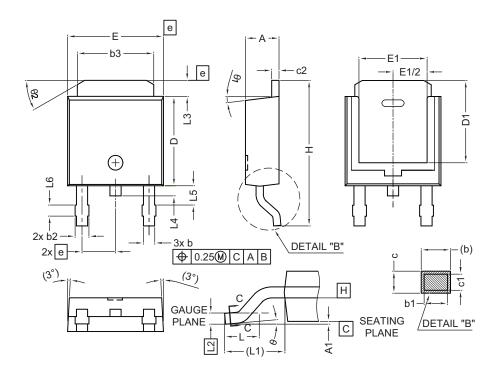
	MILLIMETERS		
DIM.	MIN.	MAX.	
A	2.18	2.38	
A1	-	0.127	
b	0.64	0.88	
b2	0.76	1.14	
b3	4.95	5.46	
С	0.46	0.61	
C2	0.46	0.89	
D	5.97	6.22	
D1	4.10	-	
Е	6.35	6.73	
E1	4.32	-	
Н	9.40	10.41	
е	2.28 BSC		
e1	4.56 BSC		
L	1.40	1.78	
L3	0.89	1.27	
L4	-	1.02	
L5	1.01	1.52	

#### Note

• Dimension L3 is for reference only



#### **VERSION 2: FACILITY CODE = N**



	MILLIMETERS		
DIM.	MIN.	MAX.	
Α	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21 -		
E	6.35 6.73		
E1	4.32 -		
е	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	ref.	
L2	0.51	BSC	
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

#### Notes

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E19-0649-Rev. Q, 16-Dec-2019

DWG: 5347



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

APPLICATION NOTE



### **Legal Disclaimer Notice**

Vishay

### **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

## Vishay:

SUD50N04-8M8P-4GE3 SUD50N04-8M8P-GE3 SUD50N04-8M8P-4BE3